

256 Kb (64K x 4) Static RAM

Features

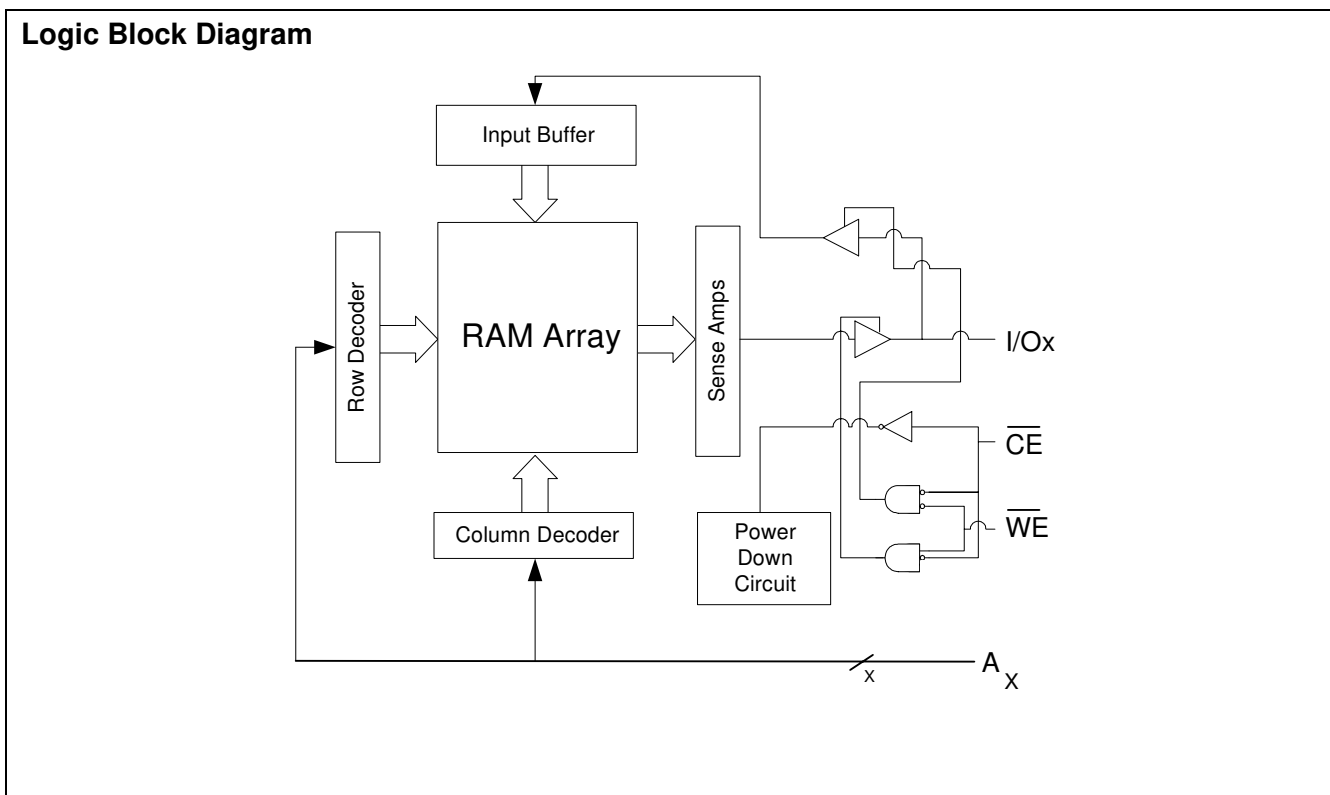
- **Fast access time: 15 ns and 25 ns**
- **Wide voltage range: 5.0V ± 10% (4.5V to 5.5V)**
- **CMOS for optimum speed/power**
- **TTL-compatible inputs and outputs**
- **CY7C194BN is available in 24 DIP, 24 SOJ packages.**

General Description [1]

The CY7C194BN is a high-performance CMOS Asynchronous SRAM organized as 64K x 4 bits that supports an asynchronous memory interface. The device features an automatic power-down feature that significantly reduces power consumption when deselected.

See the Truth Table in this data sheet for a complete description of read and write modes.

The CY7C194BN is available in 24 DIP, 24 SOJ package(s).



Product Portfolio

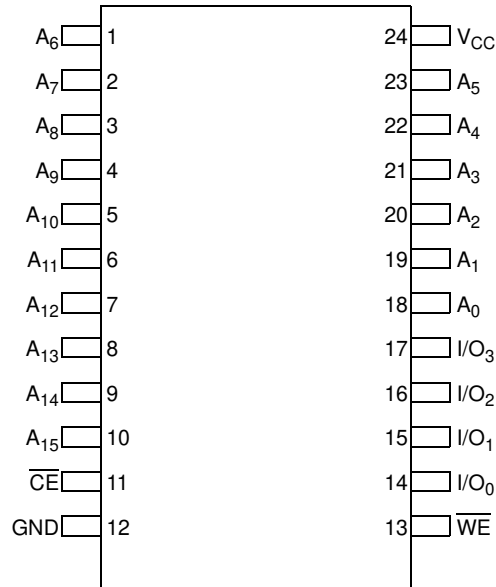
	-15	-25	Unit
Maximum Access Time	15	25	ns
Maximum Operating Current	80	80	mA
Maximum CMOS Standby Current	10	10	mA

Notes:

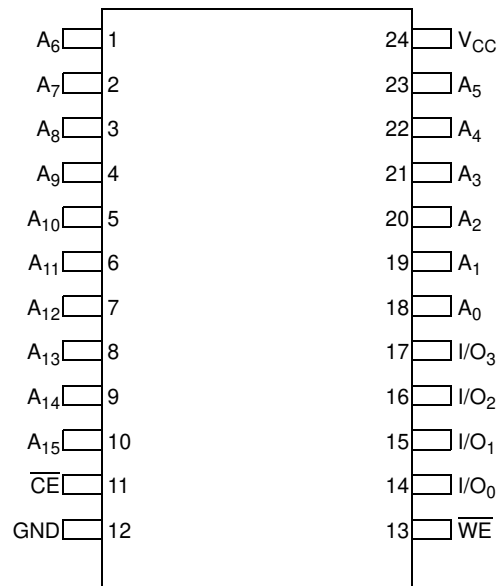
1. For best-practice recommendations, please refer to the Cypress application note *System Design Guidelines* on www.cypress.com.

Pin Layout and Specification

CY7C194BN 24 SOJ (8 × 15 × 3.5 mm)



CY7C194BN 24 DIP (6.6 × 31.8 × 3.5 mm)



Pin Description

Pin	Type	Description	CY7C194BN	
			24 DIP	24 SOJ
A _X	Input	Address Inputs.	1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 18, 19, 20, 21, 22, 23	1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 18, 19, 20, 21, 22, 23
$\overline{\text{CE}}$	Control	Chip Enable.	11	11
I/O _X	Input or Output	Data Input/Outputs.	14, 15, 16, 17	14, 15, 16, 17
NC	–	No Connect. Pins are not internally connected to the die.	–	–
V _{CC}	Supply	Power (5.0V).	24	24
$\overline{\text{WE}}$	Control	Write Enable.	13	13

CY7C194BN Truth Table

CE	WE	I/O _x	Mode	Power
H	X	High Z	Power-Down	Standby (I _{SB})
L	H	Data Out	Read	Active (I _{CC})
L	L	Data In	Write	Active (I _{CC})

Maximum Ratings (Above which the useful life may be impaired. For user guidelines, not tested.)

Parameter	Description	Value	Unit
T _{STG}	Storage Temperature	-65 to +150	°C
T _{AMB}	Ambient Temperature with Power Applied (i.e. case temperature)	-55 to +125	°C
V _{CC}	Core Supply Voltage Relative to V _{SS}	-0.5 to +7.0	V
V _{IN} , V _{OUT}	DC Voltage Applied to any Pin Relative to V _{SS}	-0.5 to V _{CC} + 0.5	V
I _{OUT}	Output Short-Circuit Current	20	mA
V _{ESD}	Static Discharge Voltage (per MIL-STD-883, Method 3015)	> 2001	V
I _{LU}	Latch-up Current	> 200	mA

Operating Range

Range	Ambient Temperature (T _A)	Voltage Range (V _{CC})
Commercial	0°C to 70°C	5.0V ± 10%

DC Electrical Characteristics^[3]

Parameter	Description	Condition	15 ns		25 ns		Unit
			Min.	Max.	Min.	Max.	
V _{IH}	Input HIGH Voltage		2.2	V _{CC} + 0.3	2.2	V _{CC} + 0.3	V
V _{IL}	Input LOW Voltage		-0.3	0.8	-0.5	0.8	V
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{oh} = -4.0 ma	2.4	-	2.4	-	V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{ol} = 8.0 ma	-	0.4	-	0.4	V
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = F _{MAX} = 1 / t _{RC}	-	80	-	80	mA
I _{SB1}	Automatic \overline{CE} Power-down Current TTL Inputs	V _{CC} = Max., $\overline{CE} \geq V_{IH}$, V _{IN} ≥ V _{IH} or V _{IN} ≤ V _{IL} , f = F _{MAX}	-	30	-	30	mA
I _{SB2}	Automatic \overline{CE} Power-down Current CMOS Inputs	V _{CC} = Max., $\overline{CE} \geq V_{CC} - 0.3v$, V _{IN} > V _{CC} - 0.3v or V _{IN} ≤ 0.3, f = 0, Commercial	-	10	-	10	mA
I _{OZ}	Output Leakage Current	GND ≤ V _i ≤ V _{CC} , Output Disabled	-5	+5	-5	+5	μA
I _{IX}	Input Load Current	GND ≤ V _i ≤ V _{CC}	-5	+5	-5	+5	μA

Capacitance^[2]

Parameter	Description	Conditions	Max	Unit
C _{IN}	Input Capacitance	T _A = 25°C, f = 1 MHz, V _{CC} = 5.0V	7	pF
C _{OUT}	Output Capacitance		10	

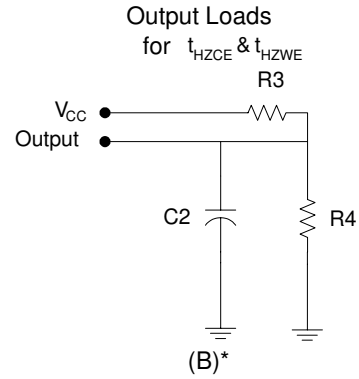
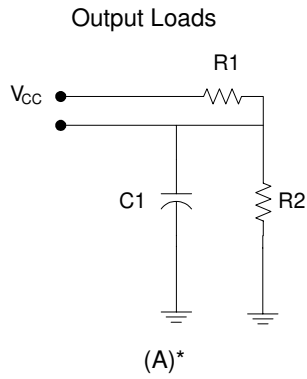
Thermal Resistance^[4]

Parameter	Description	Conditions	CY7C194BN		Unit
			24 DIP	24 SOJ	
θ _{JA}	Thermal Resistance (Junction to Ambient)	Still Air, soldered on a 3 x 4.5 square inches, two-layer printed circuit board	75.69	84.15	°C/W
θ _{JC}	Thermal Resistance (Junction to Case)		33.80	37.56	

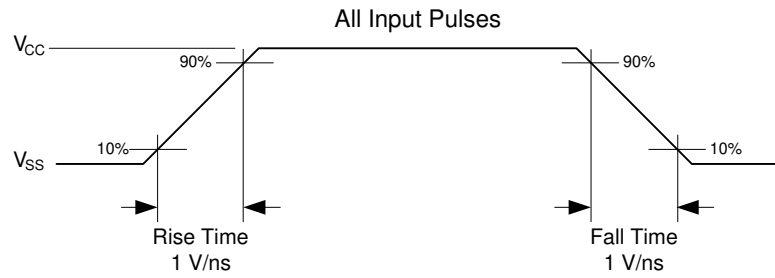
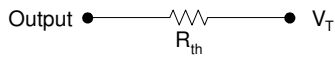
Note:

2. Tested initially and after any design or process change that may affect these parameters
3. V_{IL}(min) = -2.0V for pulse durations of less than 20 ns.
4. Test Conditions assume a transition time of 3ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V

AC Test Loads



Thevenin Equivalent



* including scope and jig capacitance

AC Test Conditions

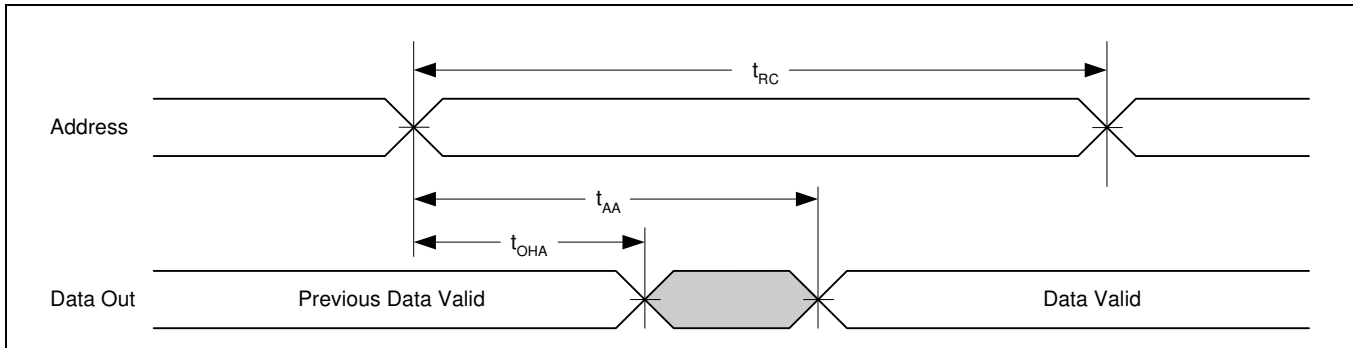
Parameter	Description	Nom.	Unit
C1	Capacitor 1	30	pF
C2	Capacitor 2	5	
R1	Resistor 1	480	Ω
R2	Resistor 2	255	
R3	Resistor 3	480	
R4	Resistor 4	255	
R _{TH}	Resistor Thevenin	167	
V _{TH}	Voltage Thevenin	1.73	V

AC Electrical Characteristics^[2, 5, 6, 7]

Parameter	Description	15 ns		25 ns		Unit
		Min	Max	Min	Max	
t_{RC}	Read Cycle Time	15	–	25	–	ns
t_{AA}	Address to Data Valid	–	15	–	25	ns
t_{OHA}	Data Hold from Address Change	3	–	3	–	ns
t_{ACE}	\overline{CE} to Data Valid	–	15	–	25	ns
t_{LZCE}	\overline{CE} to Low Z	3	–	3	–	ns
t_{HZCE}	\overline{CE} to High Z	–	7	–	10	ns
t_{PU}	\overline{CE} to Power-up	0	–	0	–	ns
t_{PD}	\overline{CE} to Power-down	–	15	–	25	ns
t_{WC}	Write Cycle Time	15	–	25	–	ns
t_{SCE}	\overline{CE} to Write End	10	–	18	–	ns
t_{AW}	Address Set-up to Write End	10	–	20	–	ns
t_{HA}	Address Hold from Write End	0	–	0	–	ns
t_{SA}	Address Set-up to Write Start	0	–	0	–	ns
t_{PWE}	\overline{WE} Pulse Width	9	–	18	–	ns
t_{SD}	Data Set-Up to Write End	8	–	10	–	ns
t_{HD}	Data Hold from Write End	0	–	0	–	ns
t_{HZWE}	\overline{WE} LOW to High Z	–	7	–	10	ns
t_{LZWE}	\overline{WE} HIGH to Low Z	3	–	3	–	ns

Timing Waveforms

Read Cycle No. 1^[8, 9]

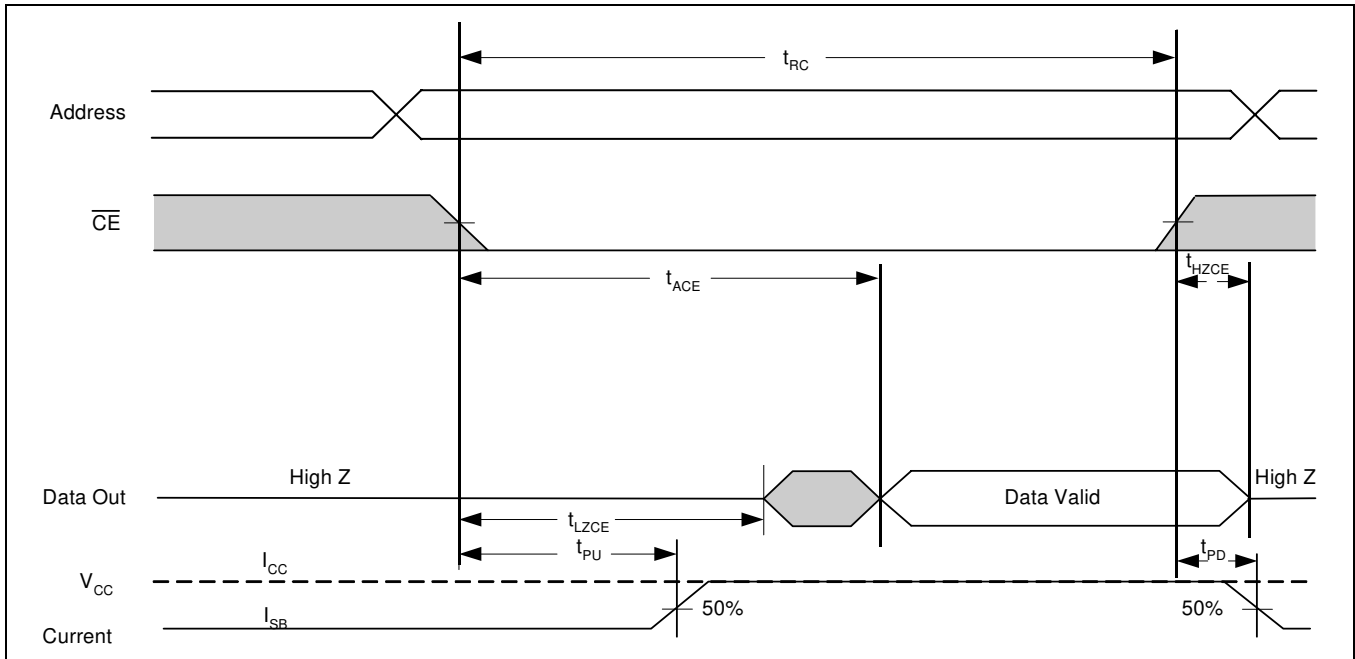


Notes:

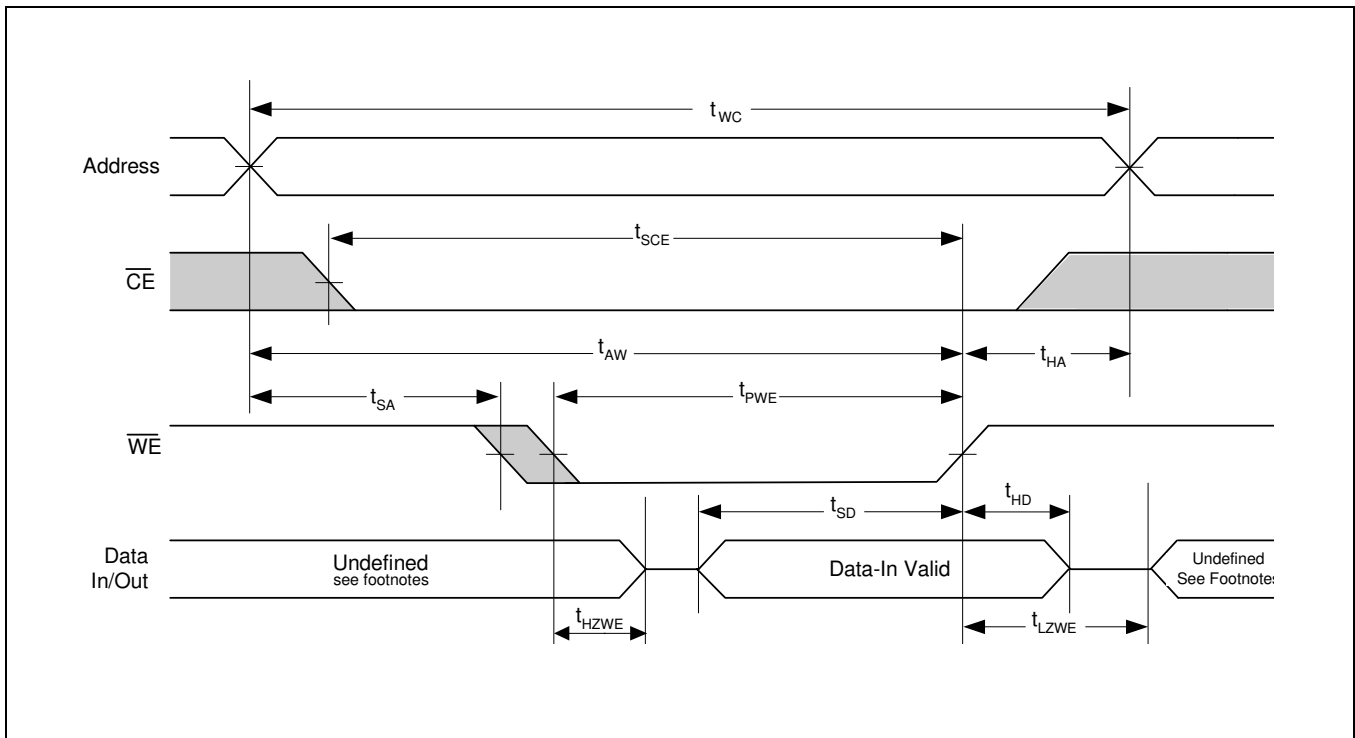
5. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , and t_{HZWE} is less than t_{LZWE} for any given device.
6. The internal write time of the memory is defined by the overlap of \overline{CE} LOW and \overline{WE} LOW. \overline{CE} and \overline{WE} must be LOW to initiate a write, and the transition of any of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
7. t_{HZCE} , t_{HZWE} are specified as in part (b) of the A/C Test Loads. Transitions are measured ± 200 mV from steady state voltage.
8. Device is continuously selected. $\overline{CE} = V_{IL}$.
9. \overline{WE} is HIGH for Read Cycle.

Timing Waveforms (continued)

Read Cycle No. 2^[2, 10, 11]



Write Cycle No. 1 (WE Controlled)^[2, 12]

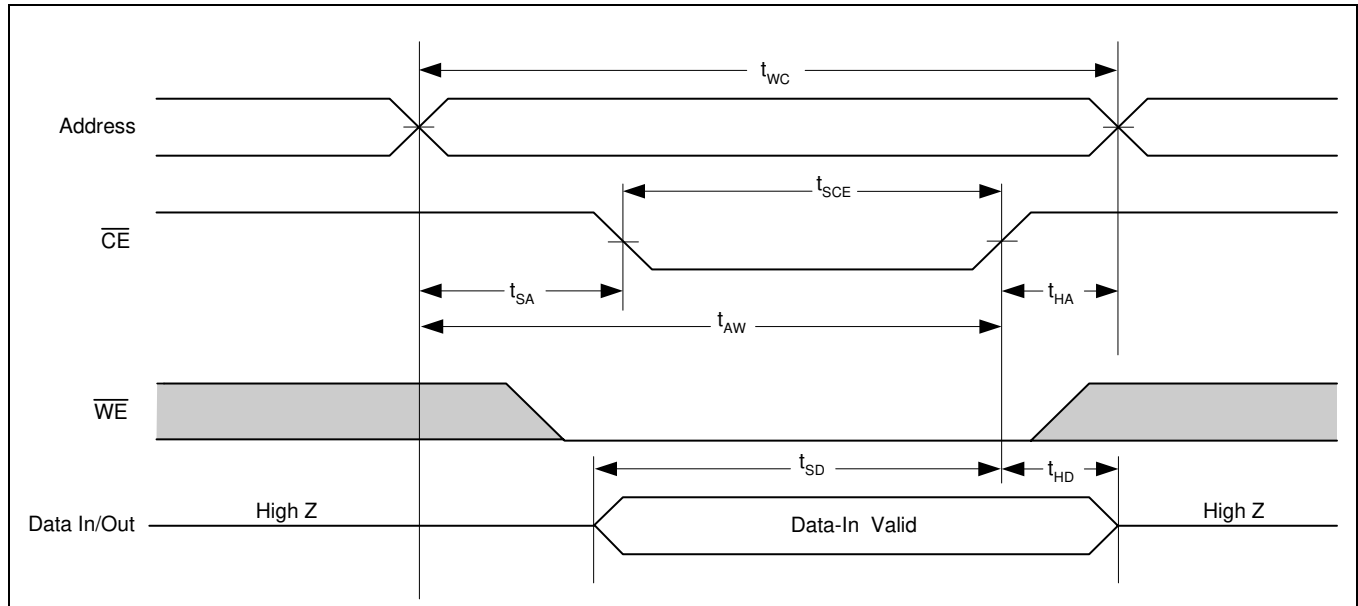


Notes:

- 10. WE is HIGH in read cycle.
- 11. Address valid prior to or coincident with CE transition LOW.
- 12. The minimum write cycle time is the sum of tHZWE and tSD.

Timing Waveforms (continued)

Write Cycle No. 2 (\overline{CE} Controlled)^[13, 14]



Notes:

- 13. This cycle is \overline{CE} controlled.
- 14. If \overline{CE} goes HIGH simultaneously with \overline{WE} going HIGH, the output remains in a high-impedance state.

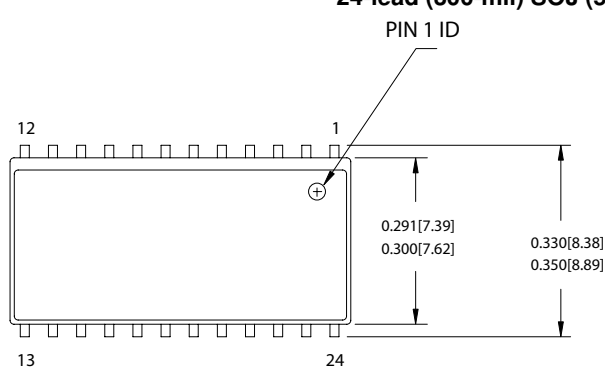
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Power Option	Operating Range
15	CY7C194BN-15PC	51-85013	24 DIP (6.6 x 31.8 x 3.5 mm)	Standard	Commercial
	CY7C194BN-15VC	51-85030	24 SOJ (8 x 15 x 3.5 mm)	Standard	Commercial
25	CY7C194BN-25VC	51-85030	24 SOJ (8 x 15 x 3.5 mm)	Standard	Commercial

Please contact local sales representative regarding availability of these parts.

Package Diagrams

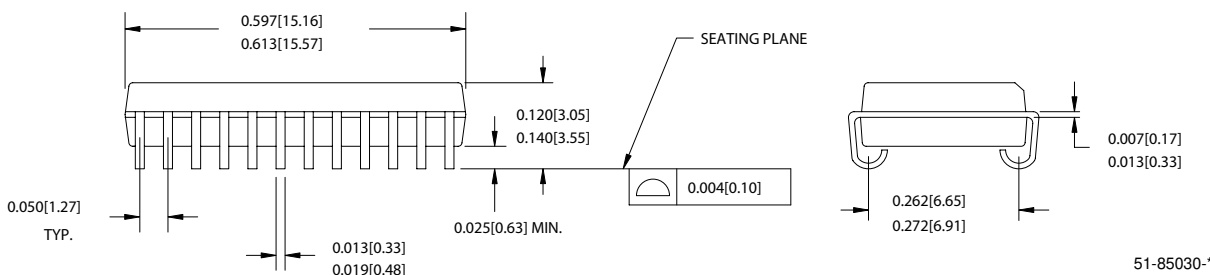
24-lead (300-mil) SOJ (51-85030)



DIMENSIONS IN INCHES[MM] MIN.
MAX.

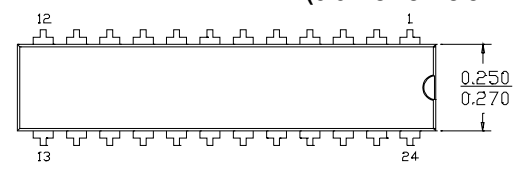
REFERENCE JEDEC MO-088
PACKAGE WEIGHT 0.75gms

PART #	
V24.3	STANDARD PKG.
VZ24.3	LEAD FREE PKG.

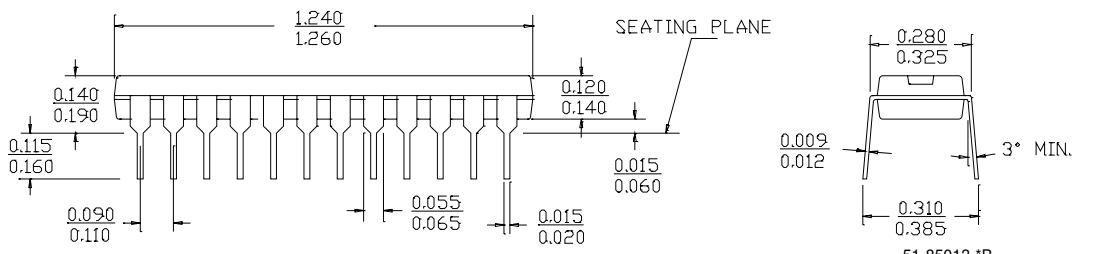


51-85030-B

24 DIP (6.6 x 31.8 x 3.5 mm) (51-85013)



DIMENSIONS IN INCHES MIN.
MAX.



51-85013-B

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Document History Page

Document Title: CY7C194BN 256 Kb (64K x 4) Static RAM Document Number: 001-06446				
REV.	ECN No.	Issue Date	Orig. of Change	Description of Change
**	424111	See ECN	NXR	New Data Sheet